

ABSTRACT OF THE DISCLOSURE

A semiconductor chip is mounted in face-up disposition on a dielectric element, with thermally conductive but flexible elements disposed between the chip bottom surface and the top surface of the dielectric element so as to provide a compliant but thermally conductive path from the chip to a substrate which is bonded to the terminals. A spreader having coefficient of thermal expansion substantially equal to that of the chip overlies the front surface and constrains an encapsulant surrounding the leads so as to minimize shear deformation of the encapsulant.

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